Samtec Brings Its High-Speed Connectors to Adiuvo Engineering's New Explorer Board for FPGA-based Systems to edge lab LIVE! at electronica 2026

NEW ALBANY, Ind. — November 3, 2026 — Samtec, Inc., the service leader in the connector industry, welcomes attendees of edge lab LIVE! (November 10-13 at electronica in Munich, Germany) to experience Adiuvo Engineering's Explorer Board, featuring several Samtec high-speed board-to-board connectors popular in embedded applications. Please visit Samtec at Hall C5.100/28.

"Our technology collaboration with Adiuvo Engineering brings essential connectivity solutions to the Explorer Board, allowing engineers to efficiently evaluate and develop with the latest FPGAs and interconnect solutions," said Matt Burns, global director of technical marketing at Samtec. "This exciting new FPGA platform features four Pmod connectors (Samtec TSW series/SSW series) and two HSIO Transceivers (Samtec QSH series/QSE series), all in a USB-C-powered board, opening the benefits of FPGAs to all developers."

Samtec's COM-HPC and OHFMC Connectivity Solutions

Samtec will demonstrate its COM-HPC® Standard Products at its booth, including its COM-HPC Server and Client modules, which use a pair of 400-pin connectors (800 pins total) based on Samtec's AcceleRate® HP High-Performance Arrays. COM-HPC Mini modules with a single connector will also be featured. Samtec COM-HPC connectors support existing and future interfaces such as PCIe® 5.0 (32 Gbps), PCIe 6.0 (64 Gbps PAM4), 25 GbE channels, 40 Gbps USB4/Thunderbolt, 80 Gbps DisplayPort signals, and other high-bandwidth interfaces. The connector pinouts are optimized for Mini, Client or Server modules as defined in the COM-HPC specification.

Samtec will also display its Open Harmonized FPGA Modules (oHFM™) Standard Products, which offer a combined approach for low- to high-ranged FPGA

modules with solderable and connector-based embedded System-on-Modules (SoMs). The oHFM.c connector-based SoMs are designed for high-speed (up to 112 Gbps PAM4 data rates), scalability, and easy upgrades.

“Samtec is the global leader in high-speed interconnects with support across all embedded computing and IoT platforms,” said Brandon Lewis, co-founder of edge lab LIVE! and president of ThroughPut Marketing. “If we didn’t have Samtec, we wouldn’t have a thriving embedded systems industry. Attendees who visit Samtec’s booth will discover the growing importance of proper interconnect selection in embedded computing applications.”

About edge lab LIVE!

edge lab LIVE! is a multi-faceted program designed for technical leaders and developers in the fields of embedded systems, the IoT and edge artificial intelligence (AI). edge lab LIVE! is jointly hosted by ThroughPut Marketing and Messe München. It takes place November 10-13, 2026 at electronica (Trade Fair Center Messe München, Munich, Germany). For more information visit: https://electronica.de/en/trade-fair/program/edge-lab/

About Samtec, Inc.

Samtec is a $1 billion global manufacturer of a broad line of electronic interconnect solutions, including High-Speed Board-to-Board, High-Speed Cables, Mid-Board and Panel Optics, Precision RF, Flexible Stacking, and Micro/Rugged components and cables. With 40+ international locations and products sold in more than 125 countries, Samtec’s global presence enables its unmatched customer service. Samtec delivers next-generation, high-quality interconnect solutions for the datacom, telecommunications, computer, semiconductor, medical, industrial, automotive, and instrumentation industries, among others. For more information, please visit: www.samtec.com.

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